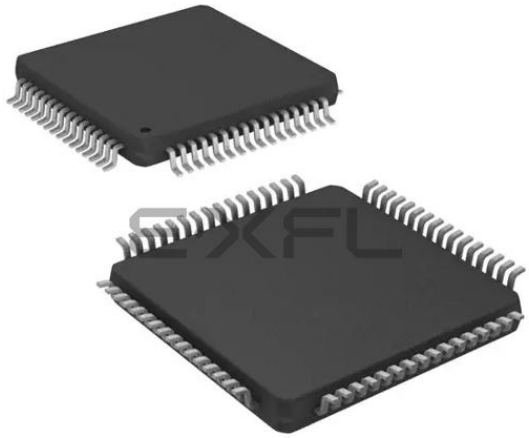
Microchip Technology - PIC32MX450F256HT-I/PT Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	49
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx450f256ht-i-pt

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MCUS

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

2.1 Basic Connection Requirements

Getting started with the PIC32MX330/350/370/430/450/470 family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins, even if the ADC module is not used (see **2.2 "Decoupling Capacitors"**)
- VCAP pin (see **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**)
- $\overline{\text{MCLR}}$ pin (see **2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins, used for In-Circuit Serial Programming (ICSP™) and debugging purposes (see **2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins, when external oscillator source is used (see **2.8 "External Oscillator Pins"**)

The following pins may be required:

VREF+/VREF- pins, used when external voltage reference for the ADC module is implemented.

Note: The AVDD and AVSS pins must be connected, regardless of ADC use and the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 µF (100 nF), 10-20V is recommended. The capacitor should be a low Equivalent Series Resistance (low-ESR) capacitor and have resonance frequency in the range of 20 MHz and higher. It is further recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended that the capacitors be placed on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

4.2 Bus Matrix Registers

TABLE 4-2: BUS MATRIX REGISTER MAP

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
2000	BMXCON(1)	31:16	—	—	—	—	—	BMXCHEDMA	—	—	—	—	—	BMXERRIXI	BMXERRICD	BMXERRDMA	BMXERRDS	BMXERRIS	041F
		15:0	—	—	—	—	—	—	—	—	—	BMXWSDRM	—	—	—	BMXARB<2:0>			0047
2010	BMXDKPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDKPBA<15:0>																0000
2020	BMXDUDBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDUDBA<15:0>																0000
2030	BMXDUPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDUPBA<15:0>																0000
2040	BMXDRMSZ	31:16	BMXDRMSZ<31:0>																xxxx
		15:0																	xxxx
2050	BMXPUPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	BMXPUPBA<19:16>				0000
		15:0	BMXPUPBA<15:0>																0000
2060	BMXPFMSZ	31:16	BMXPFMSZ<31:0>																xxxx
		15:0																	xxxx
2070	BMXBOOTSZ	31:16	BMXBOOTSZ<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 8-3: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	RODIV<14:8>(1,3)						
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	RODIV<7:0>(3)							
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0, HC	R-0, HS, HC
	ON	—	SIDL	OE	RSLP(2)	—	DIVSWEN	ACTIVE
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	ROSEL<3:0>(1)			

Legend:	HC = Hardware Clearable	HS = Hardware Settable	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **Unimplemented:** Read as '0'

bit 30-16 **RODIV<14:0>:** Reference Clock Divider bits(1,3)
This value selects the Reference Clock Divider bits. See Figure 8-1 for more information.

bit 15 **ON:** Output Enable bit
1 = Reference Oscillator Module is enabled
0 = Reference Oscillator Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Peripheral Stop in Idle Mode bit
1 = Discontinue module operation when device enters Idle mode
0 = Continue module operation in Idle mode

bit 12 **OE:** Reference Clock Output Enable bit
1 = Reference clock is driven out on REFCLKO pin
0 = Reference clock is not driven out on REFCLKO pin

bit 11 **RSLP:** Reference Oscillator Module Run in Sleep bit(2)
1 = Reference Oscillator Module output continues to run in Sleep
0 = Reference Oscillator Module output is disabled in Sleep

bit 10 **Unimplemented:** Read as '0'

bit 9 **DIVSWEN:** Divider Switch Enable bit
1 = Divider switch is in progress
0 = Divider switch is complete

bit 8 **ACTIVE:** Reference Clock Request Status bit
1 = Reference clock request is active
0 = Reference clock request is not active

bit 7-4 **Unimplemented:** Read as '0'

Note 1: The ROSEL and RODIV bits should not be written while the ACTIVE bit is '1', as undefined behavior may result.

2: This bit is ignored when the ROSEL<3:0> bits = 0000 or 0001.

3: While the ON bit is set to '1', writes to these bits do not take effect until the DIVSWEN bit is also set to '1'.

REGISTER 10-9: DCHxINT: DMA CHANNEL 'x' INTERRUPT CONTROL REGISTER (CONTINUED)

bit 4 **CHDHIF:** Channel Destination Half Full Interrupt Flag bit
- 1 = Channel Destination Pointer has reached midpoint of destination (CHDPTR = CHDSIZ/2)
- 0 = No interrupt is pending

bit 3 **CHBCIF:** Channel Block Transfer Complete Interrupt Flag bit
- 1 = A block transfer has been completed (the larger of CHSSIZ/CHDSIZ bytes has been transferred), or a pattern match event occurs
- 0 = No interrupt is pending

bit 2 **CHCCIF:** Channel Cell Transfer Complete Interrupt Flag bit
- 1 = A cell transfer has been completed (CHCSIZ bytes have been transferred)
- 0 = No interrupt is pending

bit 1 **CHTAIF:** Channel Transfer Abort Interrupt Flag bit
- 1 = An interrupt matching CHAIRQ has been detected and the DMA transfer has been aborted
- 0 = No interrupt is pending

bit 0 **CHERIF:** Channel Address Error Interrupt Flag bit
- 1 = A channel address error has been detected
  Either the source or the destination address is invalid.
- 0 = No interrupt is pending

REGISTER 11-8: U1EIR: USB ERROR INTERRUPT STATUS REGISTER (CONTINUED)

bit 1 **CRC5EF:** CRC5 Host Error Flag bit(4)
1 = Token packet is rejected due to CRC5 error
0 = Token packet is accepted
EOFEF: EOF Error Flag bit(3,5)
1 = EOF error condition is detected
0 = No EOF error condition

bit 0 **PIDEF:** PID Check Failure Flag bit
1 = PID check is failed
0 = PID check is passed

Note 1: This type of error occurs when the module's request for the DMA bus is not granted in time to service the module's demand for memory, resulting in an overflow or underflow condition, and/or the allocated buffer size is not sufficient to store the received data packet causing it to be truncated.

2: This type of error occurs when more than 16-bit-times of Idle from the previous End-of-Packet (EOP) has elapsed.

3: This type of error occurs when the module is transmitting or receiving data and the SOF counter has reached zero.

4: Device mode.

5: Host mode.

TABLE 12-11: PORTF REGISTER MAP FOR PIC32MX330F064L, PIC32MX350F128L, PIC32MX350F256L, AND PIC32MX370F512L DEVICES ONLY

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6510	TRISF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	TRISF13	TRISF12	—	—	—	TRISF8	TRISF7	TRISF6	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	xxxx
6520	PORTF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	RF13	RF12	—	—	—	RF8	RF7	RF6	RF5	RF4	RF3	RF2	RF1	RF0	xxxx
6530	LATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	LATF13	LATF12	—	—	—	LATF8	LATF7	LATF6	LATF5	LATF4	LATF3	LATF2	LATF1	LATF0	xxxx
6540	ODCF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	ODCF13	ODCF12	—	—	—	ODCF8	ODCF7	ODCF6	ODCF5	ODCF4	ODCF3	ODCF2	ODCF1	ODCF0	xxxx
6550	CNPUF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	CNPUF13	CNPUF12	—	—	—	CNPUF8	CNPUF7	CNPUF6	CNPUF5	CNPUF4	CNPDF3	CNPUF2	CNPUF1	CNPUF0	xxxx
6560	CNPDF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	CNPDF13	CNPDF12	—	—	—	CNPDF8	CNPDF7	CNPDF6	CNPDF5	CNPDF4	CNPDF3	CNPDF2	CNPDF1	CNPDF0	xxxx
6570	CNCONF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
6580	CNENF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	CNIEF13	CNIEF12	—	—	—	CNIEF8	CNIEF7	—	CNIEF5	CNIEF4	CNIEF3	CNIEF2	CNIEF1	CNIEF0	xxxx
6590	CNSTATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	CN STATF13	CN STATF12	—	—	—	CN STATF8	CN STATF7	—	CN STATF5	CN STATF4	CN STATF3	CN STATF2	CN STATF1	CN STATF0	xxxx

Legend: x = Unknown value on Reset; — = Unimplemented, read as '0'; Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 14-1: TxCON: TYPE B TIMER CONTROL REGISTER (CONTINUED)

bit 3 **T32:** 32-Bit Timer Mode Select bit(2)
1 = Odd numbered and even numbered timers form a 32-bit timer
0 = Odd numbered and even numbered timers form a separate 16-bit timer

bit 2 **Unimplemented:** Read as '0'

bit 1 **TCS:** Timer Clock Source Select bit(3)
1 = External clock from TxCK pin
0 = Internal peripheral clock

bit 0 **Unimplemented:** Read as '0'

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: This bit is available only on even numbered timers (Timer2 and Timer4).

3: While operating in 32-bit mode, this bit has no effect for odd numbered timers (Timer3 and Timer5). All timer functions are set through the even numbered timers.

4: While operating in 32-bit mode, this bit must be cleared on odd numbered timers to enable the 32-bit timer in Idle mode.

15.0 WATCHDOG TIMER (WDT)

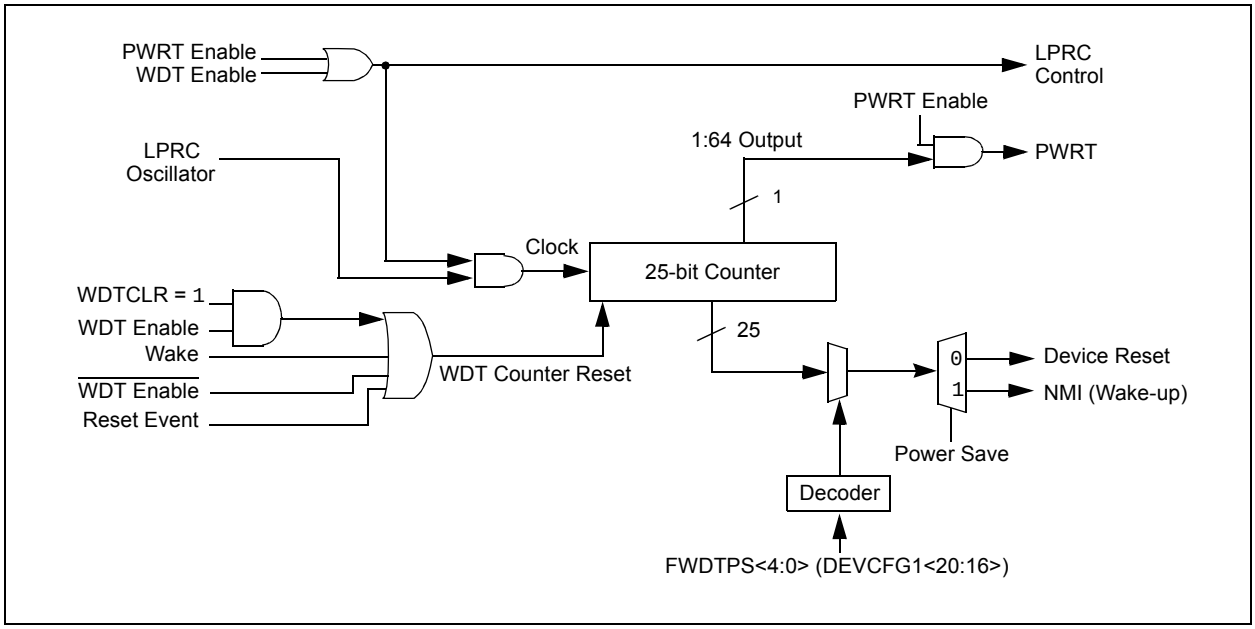
Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 9. "Watchdog, Deadman, and Power-up Timers"** (DS60001114), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The WDT, when enabled, operates from the internal Low-Power Oscillator (LPRC) clock source and can be used to detect system software malfunctions by resetting the device if the WDT is not cleared periodically in software. Various WDT time-out periods can be selected using the WDT postscaler. The WDT can also be used to wake the device from Sleep or Idle mode.

The following are some of the key features of the WDT module:

- Configuration or software controlled
- User-configurable time-out period
- Can wake the device from Sleep or Idle

FIGURE 15-1: WATCHDOG AND POWER-UP TIMER BLOCK DIAGRAM



17.0 OUTPUT COMPARE

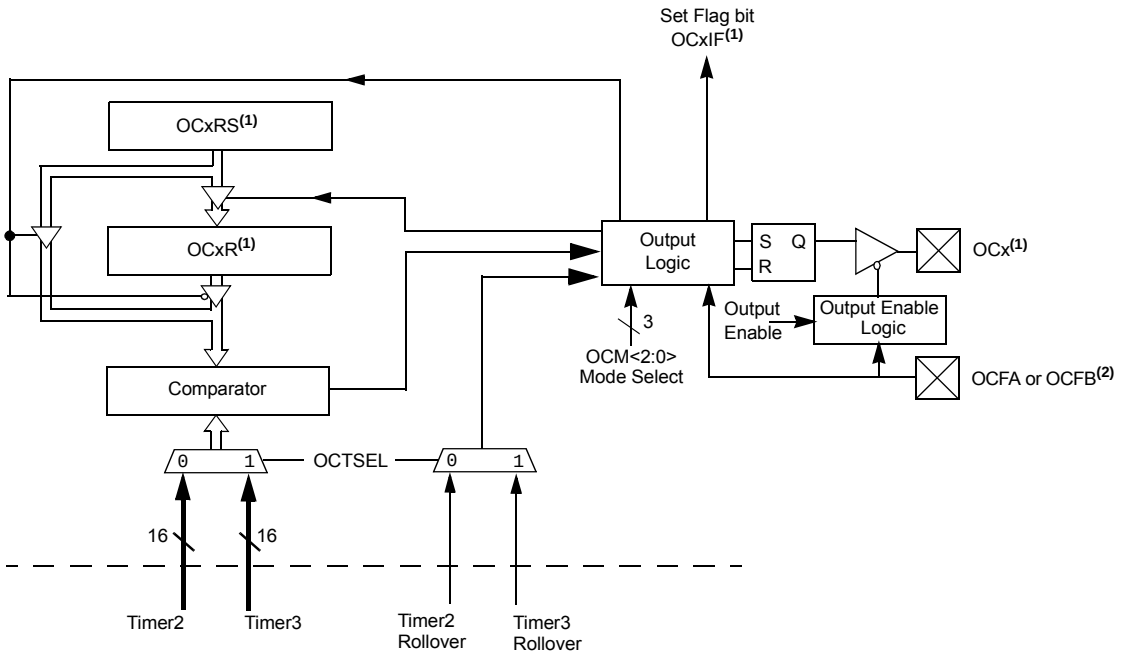
Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 16. "Output Compare"** (DS60001111), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The Output Compare module is used to generate a single pulse or a train of pulses in response to selected time base events. For all modes of operation, the Output Compare module compares the values stored in the OCxR and/or the OCxRS registers to the value in the selected timer. When a match occurs, the Output Compare module generates an event based on the selected mode of operation.

The following are key features of this module:

- Multiple Output Compare modules in a device
- Programmable interrupt generation on compare event
- Single and Dual Compare modes
- Single and continuous output pulse generation
- Pulse-Width Modulation (PWM) mode
- Hardware-based PWM Fault detection and automatic output disable
- Can operate from either of two available 16-bit time bases or a single 32-bit time base

FIGURE 17-1: OUTPUT COMPARE MODULE BLOCK DIAGRAM



Note 1: Where 'x' is shown, reference is made to the registers associated with the respective output compare channels, 1 through 5.

2: The OCFA pin controls the OC1-OC4 channels. The OCFB pin controls the OC5 channel.

REGISTER 18-3: SPIxSTAT: SPI STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
	—	—	—	RXBUFELM<4:0>				
23:16	U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
	—	—	—	TXBUFELM<4:0>				
15:8	U-0	U-0	U-0	R/C-0, HS	R-0	U-0	U-0	R-0
	—	—	—	FRMERR	SPIBUSY	—	—	SPITUR
7:0	R-0	R/W-0	R-0	U-0	R-1	U-0	R-0	R-0
	SRMT	SPIROV	SPIRBE	—	SPITBE	—	SPITBF	SPIRBF

Legend:	C = Clearable bit	HS = Set in hardware	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-29 **Unimplemented:** Read as '0'

bit 28-24 **RXBUFELM<4:0>:** Receive Buffer Element Count bits (valid only when ENHBUF = 1)

bit 23-21 **Unimplemented:** Read as '0'

bit 20-16 **TXBUFELM<4:0>:** Transmit Buffer Element Count bits (valid only when ENHBUF = 1)

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **FRMERR:** SPI Frame Error status bit
1 = Frame error is detected
0 = No Frame error is detected
This bit is only valid when FRMEN = 1.

bit 11 **SPIBUSY:** SPI Activity Status bit
1 = SPI peripheral is currently busy with some transactions
0 = SPI peripheral is currently idle

bit 10-9 **Unimplemented:** Read as '0'

bit 8 **SPITUR:** Transmit Under Run bit
1 = Transmit buffer has encountered an underrun condition
0 = Transmit buffer has no underrun condition
This bit is only valid in Framed Sync mode; the underrun condition must be cleared by disabling (ON bit = 0) and re-enabling (ON bit = 1) the module, or writing a '0' to SPITUR.

bit 7 **SRMT:** Shift Register Empty bit (valid only when ENHBUF = 1)
1 = When SPI module shift register is empty
0 = When SPI module shift register is not empty

bit 6 **SPIROV:** Receive Overflow Flag bit
1 = A new data is completely received and discarded. The user software has not read the previous data in the SPIxBUF register.
0 = No overflow has occurred
This bit is set in hardware; can bit only be cleared by disabling (ON bit = 0) and re-enabling (ON bit = 1) the module, or by writing a '0' to SPIROV.

bit 5 **SPIRBE:** RX FIFO Empty bit (valid only when ENHBUF = 1)
1 = RX FIFO is empty (CRPTR = SWPTR)
0 = RX FIFO is not empty (CRPTR ≠ SWPTR)

bit 4 **Unimplemented:** Read as '0'

NOTES:

REGISTER 20-1: UxMODE: UARTx MODE REGISTER (CONTINUED)

bit 5 **ABAUD:** Auto-Baud Enable bit
- 1 = Enable baud rate measurement on the next character – requires reception of Sync character (0x55); cleared by hardware upon completion
- 0 = Baud rate measurement disabled or completed

bit 4 **RXINV:** Receive Polarity Inversion bit
- 1 = UxRX Idle state is '0'
- 0 = UxRX Idle state is '1'

bit 3 **BRGH:** High Baud Rate Enable bit
- 1 = High-Speed mode – 4x baud clock enabled
- 0 = Standard Speed mode – 16x baud clock enabled

bit 2-1 **PDSEL<1:0>:** Parity and Data Selection bits
- 11 = 9-bit data, no parity
- 10 = 8-bit data, odd parity
- 01 = 8-bit data, even parity
- 00 = 8-bit data, no parity

bit 0 **STSEL:** Stop Selection bit
- 1 = 2 Stop bits
- 0 = 1 Stop bit

Note 1: When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

REGISTER 23-1: AD1CON1: ADC CONTROL REGISTER 1 (CONTINUED)

bit 4 **CLRASAM:** Stop Conversion Sequence bit (when the first ADC interrupt is generated)
1 = Stop conversions when the first ADC interrupt is generated. Hardware clears the ASAM bit when the ADC interrupt is generated.
0 = Normal operation, buffer contents will be overwritten by the next conversion sequence

bit 3 **Unimplemented:** Read as '0'

bit 2 **ASAM:** ADC Sample Auto-Start bit
1 = Sampling begins immediately after last conversion completes; SAMP bit is automatically set.
0 = Sampling begins when SAMP bit is set

bit 1 **SAMP:** ADC Sample Enable bit(2)
1 = The ADC sample and hold amplifier is sampling
0 = The ADC sample/hold amplifier is holding
When ASAM = 0, writing '1' to this bit starts sampling.
When SSRC = 000, writing '0' to this bit will end sampling and start conversion.

bit 0 **DONE:** Analog-to-Digital Conversion Status bit(3)
1 = Analog-to-digital conversion is done
0 = Analog-to-digital conversion is not done or has not started
Clearing this bit will not affect any operation in progress.

Note 1: When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC ≠ 0, this bit is automatically cleared by hardware to end sampling and start conversion.

3: This bit is automatically set by hardware when ADC is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

REGISTER 28-3: DEVCFG2: DEVICE CONFIGURATION WORD 2 (CONTINUED)

bit 2-0 **FPLLIDIV<2:0>:** PLL Input Divider bits

111 = 12x divider
110 = 10x divider
101 = 6x divider
100 = 5x divider
011 = 4x divider
010 = 3x divider
001 = 2x divider
000 = 1x divider

Note 1: This bit is available on PIC32MX4XX devices only.

30.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

30.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

31.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC32MX330/350/370/430/450/470 AC characteristics and timing parameters.

FIGURE 31-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

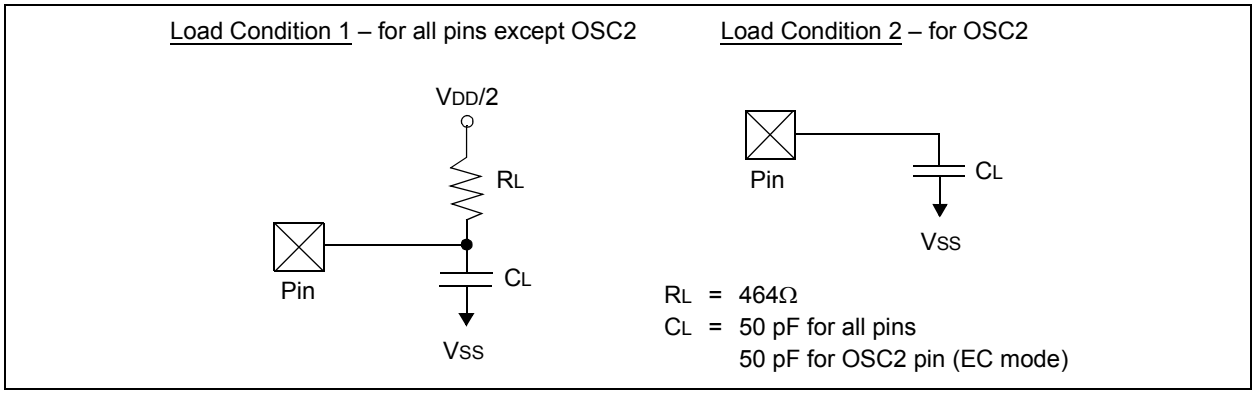


TABLE 31-17: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
DO50	COSCO	OSC2 pin	—	—	15	pF	In XT and HS modes when an external crystal is used to drive OSC1
DO56	CIO	All I/O pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLx, SDAx	—	—	400	pF	In I^2C mode

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 31-2: EXTERNAL CLOCK TIMING

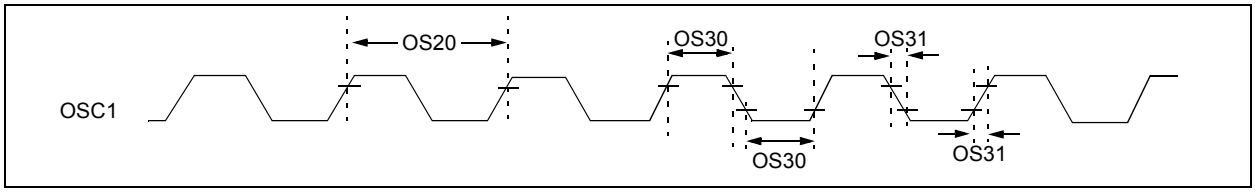
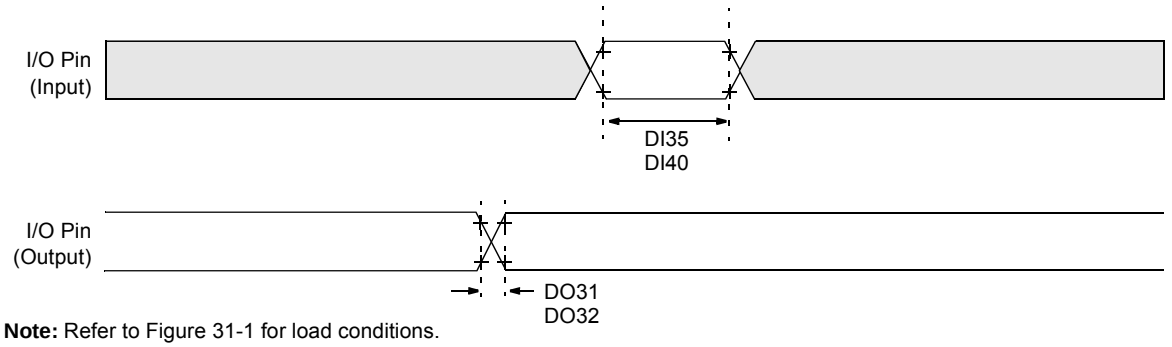


TABLE 31-21: INTERNAL LPRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
LPRC @ 31.25 kHz(1)						
F21	LPRC	-15	—	+15	%	—

Note 1: Change of LPRC frequency as VDD changes.

FIGURE 31-3: I/O TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

TABLE 31-22: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(2)**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	5	15	ns	VDD < 2.5V
			—	5	10	ns	VDD > 2.5V
DO32	TIOF	Port Output Fall Time	—	5	15	ns	VDD < 2.5V
			—	5	10	ns	VDD > 2.5V
DI35	TINP	INTx Pin High or Low Time	10	—	—	ns	—
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TSYSCLK	—

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

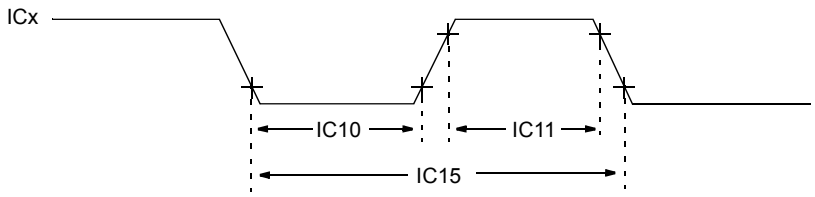
2: This parameter is characterized, but not tested in manufacturing.

TABLE 31-25: TIMER2, 3, 4, 5 EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**		**Min.**	**Max.**	**Units**	**Conditions**	
TB10	TTXH	TxCK High Time	Synchronous, with prescaler	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15	N = prescale value (1, 2, 4, 8, 16, 32, 64, 256)
TB11	TTXL	TxCK Low Time	Synchronous, with prescaler	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15	
TB15	TTXP	TxCK Input Period	Synchronous, with prescaler	[(Greater of [(25 ns or 2 TPB)/N] + 30 ns	—	ns	VDD > 2.7V	
				[(Greater of [(25 ns or 2 TPB)/N] + 50 ns	—	ns	VDD < 2.7V	
TB20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		—	1	TPB	—	

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 31-7: INPUT CAPTURE (CAPx) TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

TABLE 31-26: INPUT CAPTURE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Max.**	**Units**	**Conditions**	
IC10	TCCL	ICx Input Low Time	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter IC15.	N = prescale value (1, 4, 16)
IC11	TCCH	ICx Input High Time	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter IC15.	
IC15	TCCP	ICx Input Period	[(25 ns or 2 TPB)/N] + 50 ns	—	ns	—	

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 31-23: EJTAG TIMING CHARACTERISTICS

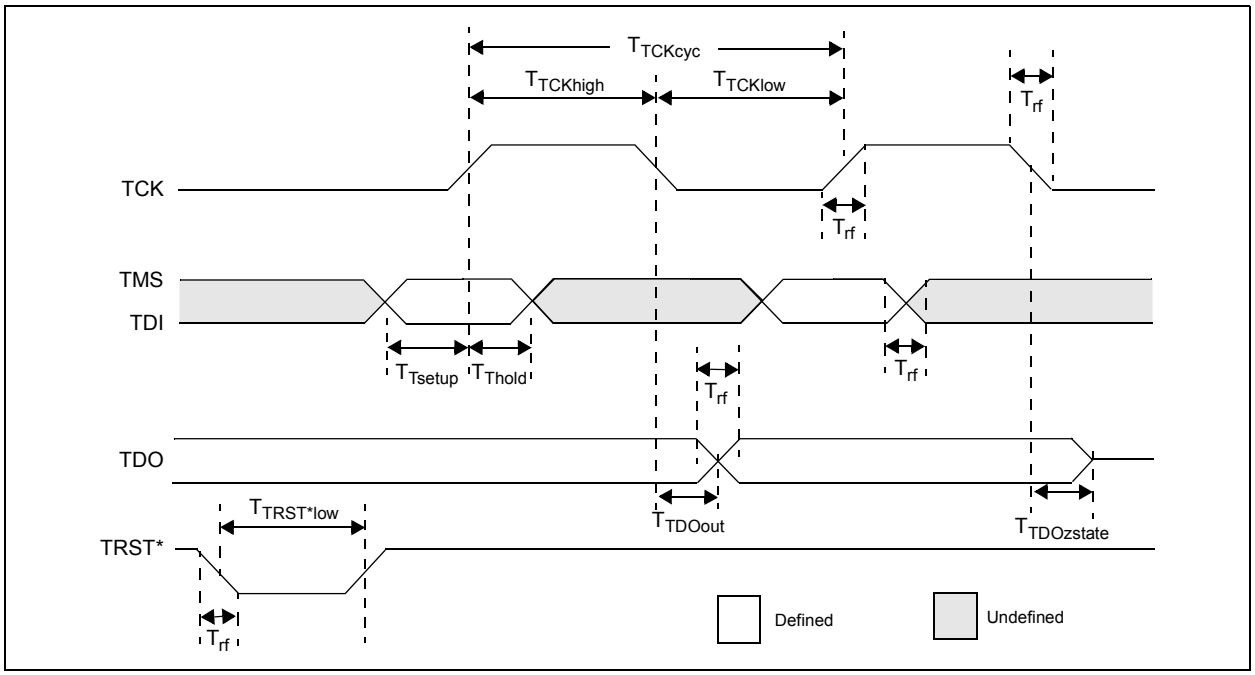


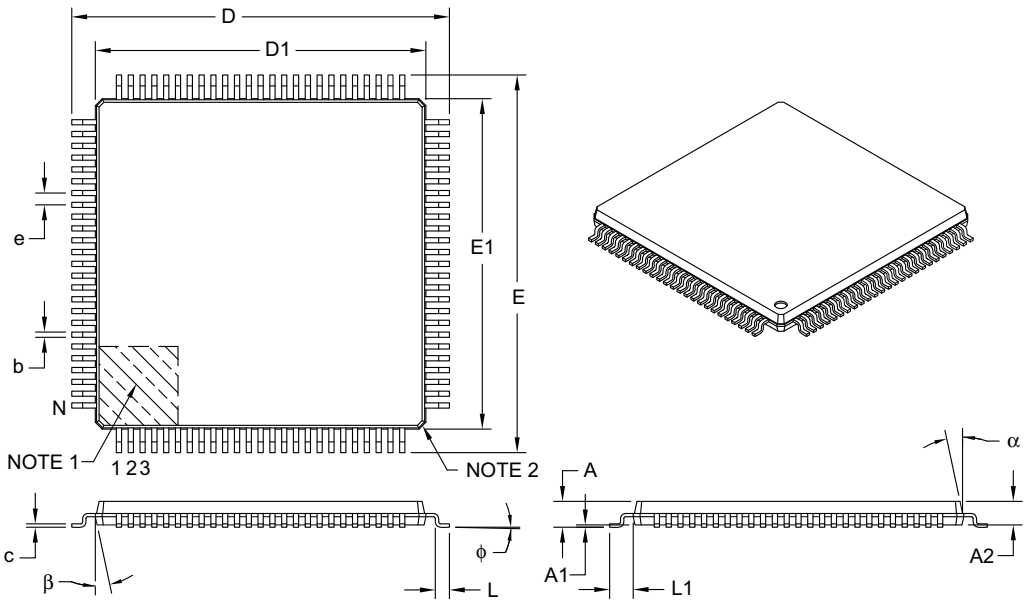
TABLE 31-43: EJTAG TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Description(1)**	**Min.**	**Max.**	**Units**	**Conditions**
EJ1	TTCKCYC	TCK Cycle Time	25	—	ns	—
EJ2	TTCKHIGH	TCK High Time	10	—	ns	—
EJ3	TTCKLOW	TCK Low Time	10	—	ns	—
EJ4	TTSETUP	TAP Signals Setup Time Before Rising TCK	5	—	ns	—
EJ5	TTHOLD	TAP Signals Hold Time After Rising TCK	3	—	ns	—
EJ6	TTDOOUT	TDO Output Delay Time from Falling TCK	—	5	ns	—
EJ7	TTDOZSTATE	TDO 3-State Delay Time from Falling TCK	—	5	ns	—
EJ8	TTRSTLOW	TRST Low Time	25	—	ns	—
EJ9	TRF	TAP Signals Rise/Fall Time, All Input and Output	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

100-Lead Plastic Thin Quad Flatpack (PF) – 14x14x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		16.00 BSC	
Overall Length	D		16.00 BSC	
Molded Package Width	E1		14.00 BSC	
Molded Package Length	D1		14.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-110B